

# FMP05N50E

**FUJI POWER MOSFET** 

## Super FAP-E<sup>3</sup> series

#### **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower  $R_{DS}(on)$  characteristic More controllable switching dv/dt by gate resistance Smaller  $V_{GS}$  ringing waveform during switching Narrow band of the gate threshold voltage (3.0±0.5V) High avalanche durability

#### Applications

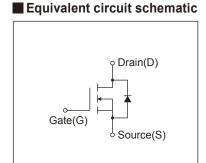
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

### ■ Maximum Ratings and Characteristics

#### ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

TO-220AB 10 \$\frac{4}{3}\$ \$\frac{1}{3}\$ \$\fr	4,5.9.2 1,3
"	CONNECTION
+ + + ① ② ③	① GATE ② DRAIN ③ SOURCE

■ Outline Drawings [mm]



#### Description Characteristics Symbol Unit Remarks $V_{\text{DS}}$ **Drain-Source Voltage** VDSX 500 V V<sub>GS</sub> = -30V **Continuous Drain Current** ΙD ±5 Α **Pulsed Drain Current** IDP ±20 Α Gate-Source Voltage Vgs ±30 V Repetitive and Non-Repetitive Maximum Avalanche Current $I_{\text{AR}}$ 5 Α Note\*1 Non-Repetitive Maximum Avalanche Energy Note\*2 171 EAS mJ Repetitive Maximum Avalanche Energy EAR 6.0 Note\*3 Peak Diode Recovery dV/dt dV/dt 5.3 Note\*4 kV/us Peak Diode Recovery -di/dt -di/dt 100 Note\*5 A/µs 2.02 Ta=25°C **Maximum Power Dissipation** $P_{D}$ W 60 Tc=25°C Tch 150 °C **Operating and Storage Temperature range** Tstg -55 to +150 °C

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BVoss	I <sub>D</sub> =250µA, V <sub>GS</sub> =0V		500	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		2.5	3.0	3.5	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA
Drain-Source On-State Resistance	Ros (on)	I <sub>D</sub> =2.5A, V <sub>GS</sub> =10V		-	1.28	1.50	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =2.5A, V <sub>DS</sub> =25V		2.5	5	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V V <sub>GS</sub> =0V f=1MHz		-	610	915	pF
Output Capacitance	Coss			-	66	99	
Reverse Transfer Capacitance	Crss			-	4.7	7.1	
Turn-On Time	td(on)	V <sub>cc</sub> =300V     -       V <sub>GS</sub> =10V     -       I <sub>D</sub> =2.5A     -       R <sub>G</sub> =24Ω     -		-	10	15	ns
	tr			-	7	10.5	
Turn-Off Time	td(off)			-	45	67.5	
	tf			13.5	20.3	1	
Total Gate Charge	Q <sub>G</sub>	V <sub>cc</sub> =250V I <sub>D</sub> =5A V <sub>cs</sub> =10V		-	21	32	nC
Gate-Source Charge	QGS			-	6	9	
Gate-Drain Charge	Q <sub>GD</sub>			-	5.5	8.3	
Avalanche Capability	lav	L=5.01mH, Tch=25°C		5	-	-	Α
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.86	1.30	V
Reverse Recovery Time	trr	I <sub>F</sub> =5A, V <sub>GS</sub> =0V		-	0.28	-	μs
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	1.8	-	μC

#### Thermal Characteristics

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Description	Symbol	Test Conditions	min.	typ.	max.	Unit	
Thermal resistance	Rth (ch-c)	Channel to Case			1.200	°C/W	
	Rth (ch-a)	Channel to Ambient			62.0	°C/W	

Note \*1 : Tch≤150°C

Note \*2 : Stating Tch=25°C, Ias=2A, L=78.3mH, Vcc=50V, R<sub>G</sub>=50Ω

Eas limited by maximum channel temperature and avalanche current.

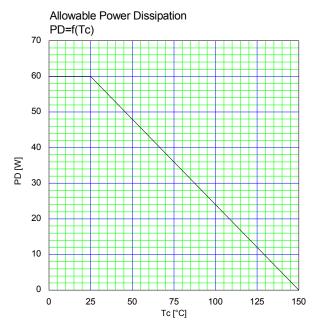
See to 'Avalanche Energy' graph.

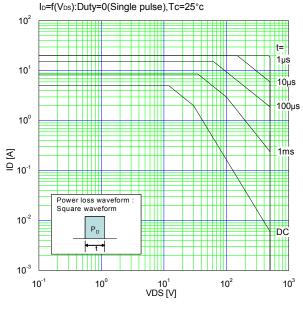
Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.

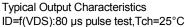
See to the 'Transient Themal impeadance' graph.

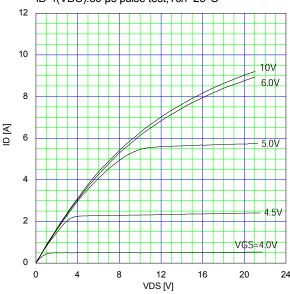
Note \*4 : IF≤-ID, -di/dt=100A/µs, Vcc≤BVbss, Tch≤150°C. Note \*5 : IF≤-ID, dv/dt=5.3kV/µs, Vcc≤BVbss, Tch≤150°C.

Safe Operating Area

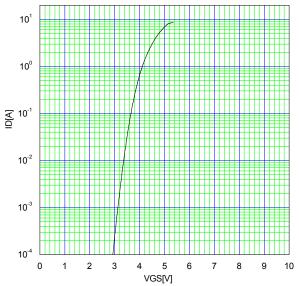




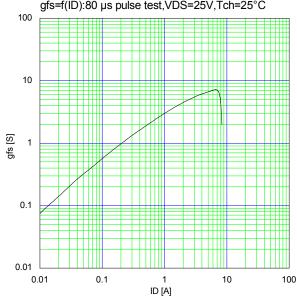




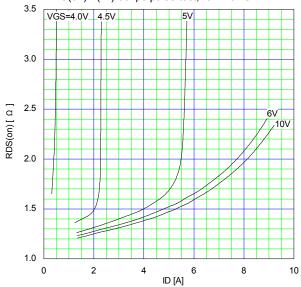
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C



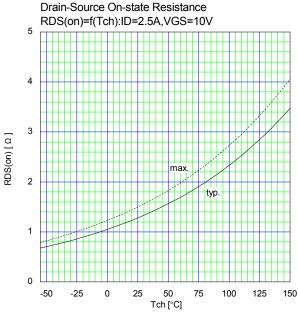
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25°C

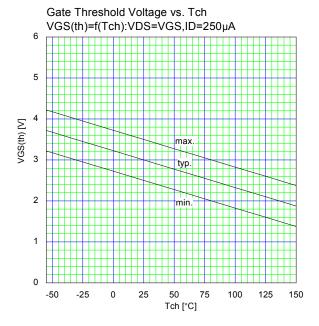


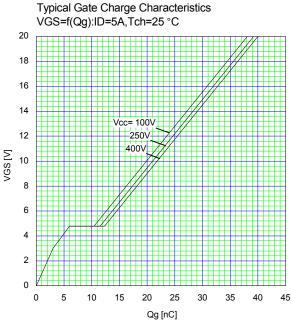
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80  $\mu$ s pulse test,Tch=25  $^{\circ}$ C

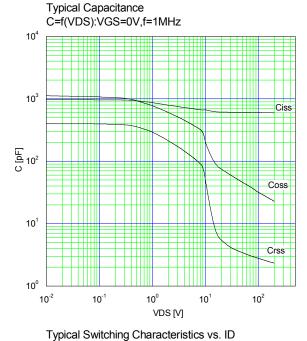


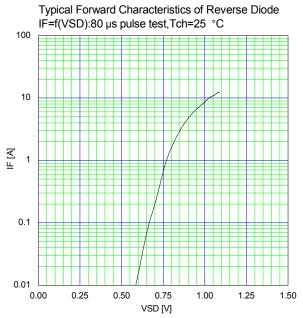
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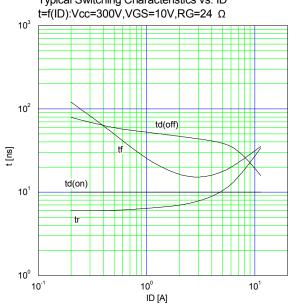




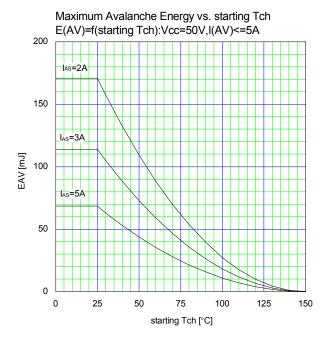


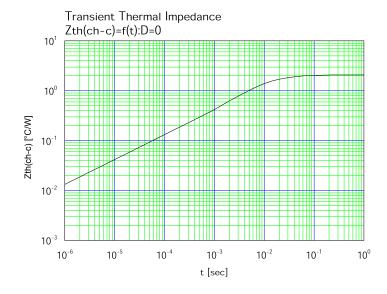






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  - Transportation equipment (mounted on cars)
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